

Electronic Patent Application Fee Transmittal

Application Number:	10787269			
Filing Date:	25-Feb-2004			
Title of Invention:	SEMICONDUCTOR PACKAGE WITH HEAT DISSIPATING STRUCTURE			
First Named Inventor/Applicant Name:	Chien-Ping Huang			
Filer:	Steven M. Jensen			
Attorney Docket Number:	58102-DIV (71987)			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	2	3	6
Total in USD (\$)				1746